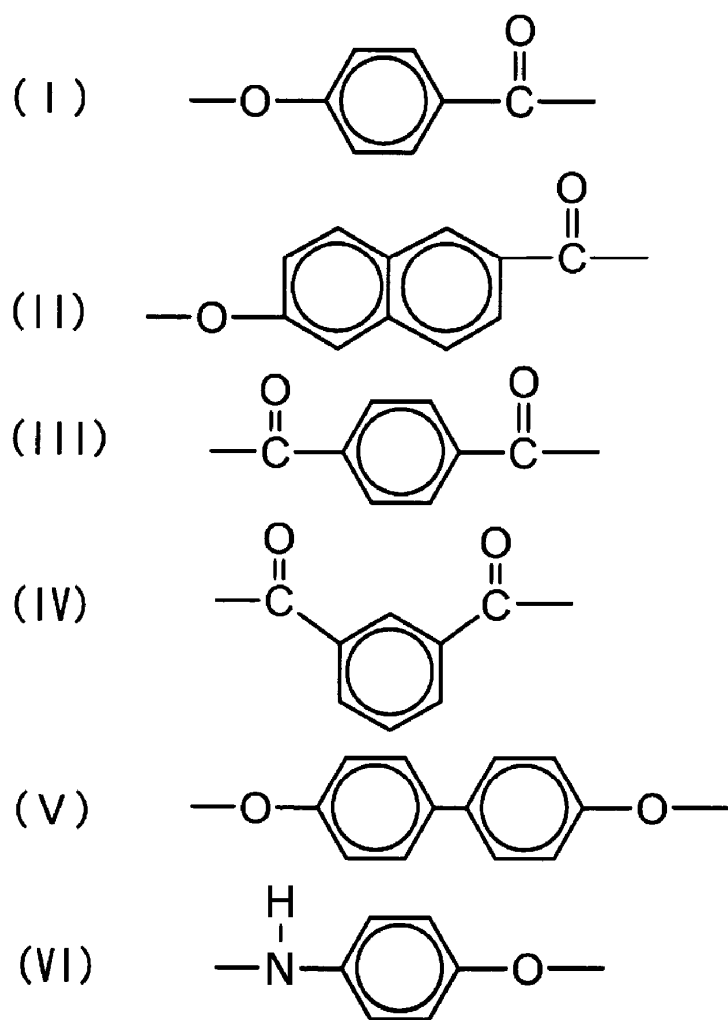


ABSTRACT

COMPOSITE RESIN COMPOSITION, AND ELECTRONIC COMPONENT FORMED
FROM SAID COMPOSITE RESIN COMPOSITION

A composite resin composition, from which it is possible to obtain an electronic component which has excellent heat resistance and in which warp deformation and blistering are suppressed, and an electronic component formed from said composite resin composition are provided. This composite resin composition contains (A) a liquid crystal polymer, (B) a fibrous filler, (C) a plate-form filler. As an essential constituent component, the liquid crystal polymer (A) contains a wholly aromatic polyester amide which comprises prescribed amounts of structural units (I) to (VI) and exhibits optical anisotropy during melting. The weight average fiber length of the fibrous filler (B) is greater than or equal to 250 μm .



[FIG. 1]